

## CT2522

Single LOW POWER +5 VOLT ONLY  
TRANSCEIVER FOR MIL-STD-1553B

### GENERAL DESCRIPTION

The CT2522 +5V only transceiver is a third generation hybrid device utilizing custom monolithic drivers and receivers. This allows the device to be operated from a single +5V supply. This design results in lower power and 100% duty cycle is permissible at 125C° case temperature. Each driver dissipates less than 1.0 watt at 25% duty cycle.

Marconi Circuit Technology Corporation is a MIL-STD-1772 Certified Manufacturer.

### FEATURES

- 24 pin double dip package or flat pack
- Monolithic +5V Only Drivers
- AC interstage coupling prevents static burnout
- Receiver filtered to improve S/N ratio of system
- 20mV typical output offset
- TTL compatible

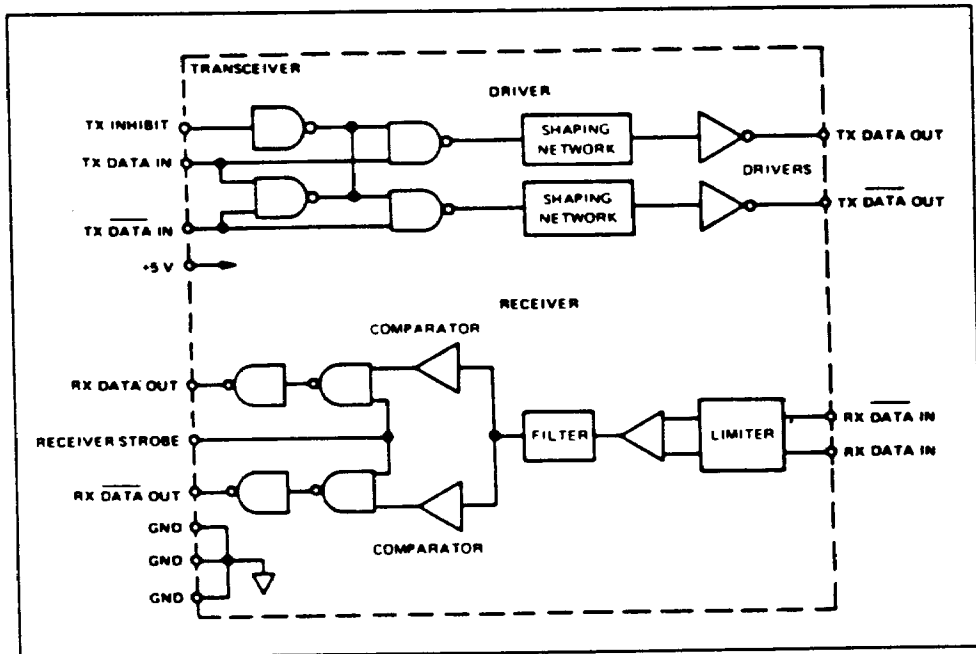


FIGURE 1. FUNCTIONAL DIAGRAM

**ELECTRICAL CHARACTERISTICS, RECEIVER SECTION**

PARAMETER/CONDITION	SYMBOL	MIN	TYP	MAX	UNIT
<b>INPUT CHARACTERISTICS</b>					
Differential input impedance DC to 1 MHz	$Z_{in}$	9K			ohms
Differential voltage range	$V_{idr}$	$\pm 20V$			$V_{peak}$
Input common mode voltage range	$V_{icr}$	$\pm 10V$			$V_{peak}$
Common mode rejection ratio (from point A)	CMRR	40			dB
<b>STROBE characteristics</b>					
(Logic "0" inhibits output)					
"0" input current ( $V_s = 0.4 V$ )	$I_{il}$			-1	ma
"1" input current ( $V_s = 2.7 V$ )	$I_{ih}$			40	$\mu A$
"0" input voltage	$V_{il}$			0.7	V
"1" input voltage	$V_{ih}$	2			V
Threshold characteristics (sine wave at 1 MHz)	$V_{th1}$	0.8	1.0	1.1	$V_{p-p}$
NOTE: Threshold voltages refer to point A.					
Filter characteristics					
(sine wave input)		2 MHz		8	$V_{p-p}$
		3 MHz			$V_{p-p}$
<b>OUTPUT CHARACTERISTICS</b>					
"1" state ( $I_{source} = 400\mu A$ )	$V_{oh}$	2.5	3.4		V
"0" state ( $I_{sink} = 4mA$ )	$V_{ol}$			0.5	V
NOTE: With receiver input below threshold both RX DATA OUT and RX DATA OUT remain in "0" state.					
Delay (average) from differential input zero crossings to RX DATA OUT and RX DATA OUT output to 50% points	$t_{DRX}$		340	450	ns

**ELECTRICAL CHARACTERISTICS, DRIVER SECTION**

PARAMETER/CONDITION	SYMBOL	MIN	TYP	MAX	UNIT
<b>INPUT CHARACTERISTICS</b>					
"0" input current ( $V_{in} = 0.4 V$ )	$I_{il}$			-1	ma
"1" input current ( $V_{in} = 2.7 V$ )	$I_{ih}$			100	$\mu A$
"0" input voltage	$V_{il}$			0.7	V
"1" input voltage	$V_{ih}$	2			V
Delay from TX INHIBIT (0 $\rightarrow$ 1) to inhibited output impedance	$t_{DXOFF}$		150	225	ns
Delay from TX INHIBIT (1 $\rightarrow$ 0) to active output impedance	$t_{DXON}$		100	150	ns
Differential output noise	$V_{noi}$			10	mV <sub>p-p</sub>
Differential output impedance (inhibited at 1 MHz)	$Z_{oi}$	5K			ohms
<b>OUTPUT CHARACTERISTICS</b>					
Differential output level at point B, (145-ohm load)	$V_o$	24	27	35	$V_{p-p}$
Rise and fall times (10% - 90% of p-p output)	$t_r$	100	160	300	ns
Output offset at point A (35-ohm load)	$V_{os}$		$\pm 20$	$\pm 75$	mV peak
2.5 $\mu s$ after mid-bit crossing of parity bit of last word of a 600 $\mu s$ message					
Delay from 50% point of TX DATA IN or TX DATA IN to zero crossing differential output	$t_{DTX}$		100	150	ns

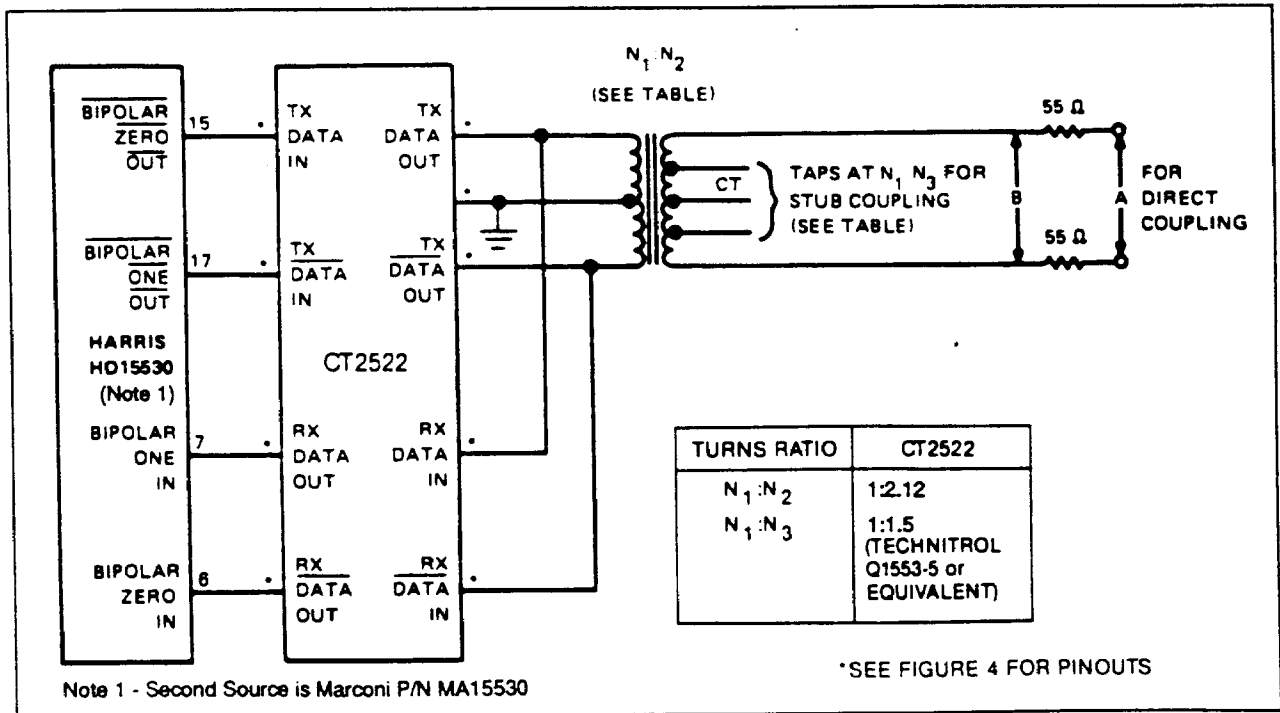
**POWER AND THERMAL DATA, TOTAL HYBRID (DRIVER AND RECEIVER)**

PARAMETER/CONDITION	SYMBOL	CT2522					
		MIN	TYP	MAX	UNIT		
Power Supply voltages	$V_{cc}$	4.5	5.0	5.5	V		
Power dissipation of most critical (hottest) device in hybrid during continuous transmission (100%) duty cycle)	$P_c$	Note 1	0.20	0.25	W		
Thermal resistance, most critical device	$\theta_{jc}$			60	$^{\circ}C/W$		
Junction to case temperature rise of most critical device at 100% duty cycle transmission	$T_{jc}$			15	$^{\circ}C$		
Total supply current "standby" mode, or transmitting at less than 1% duty cycle (e.g. 20 $\mu s$ of transmission every 2 ms or longer interval)	$I_{cc}$		110	120	mA		
Total supply current transmitting at 1 MHz into a 35-ohm load at point A		*DUTY CYCLE					
		25%	$I_{cc25}$	Note 2	225	240	mA
		100%	$I_{cc100}$	Note 2	535	610	mA

\*Dual unit (one unit transmitting)

NOTE 1: Decreases linearly to zero at zero duty cycle.

NOTE 2: Decreases linearly to applicable "standby by" value at zero duty cycle.

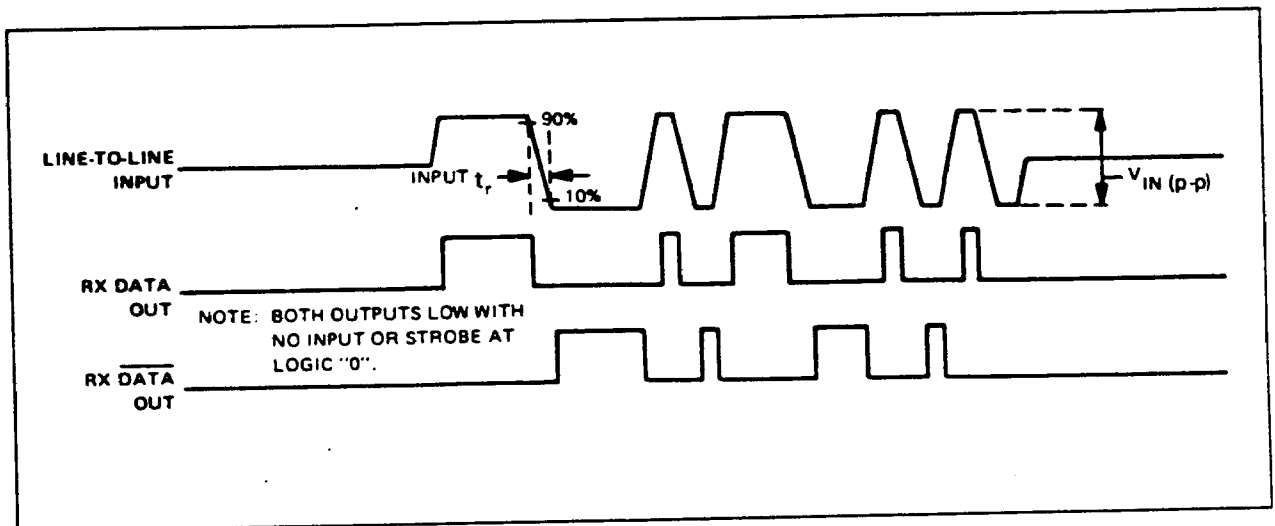


Note 1 - Second Source is Marconi P/N MA15530

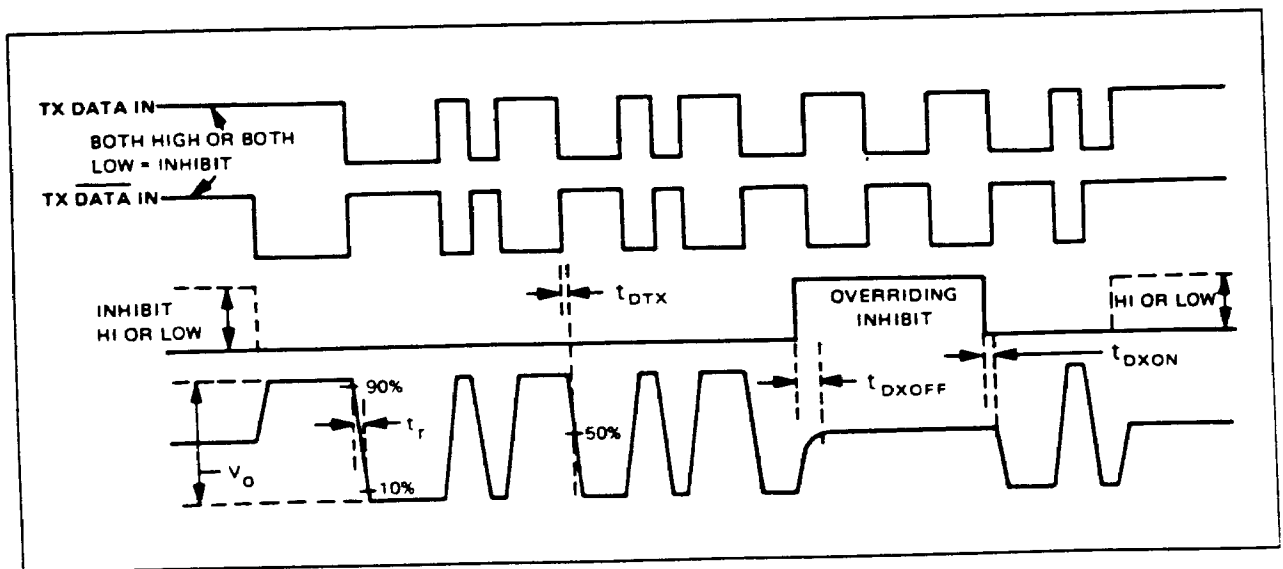
FIGURE 2. TYPICAL INPUT/OUTPUT CONNECTIONS

### Absolute Maximum Ratings

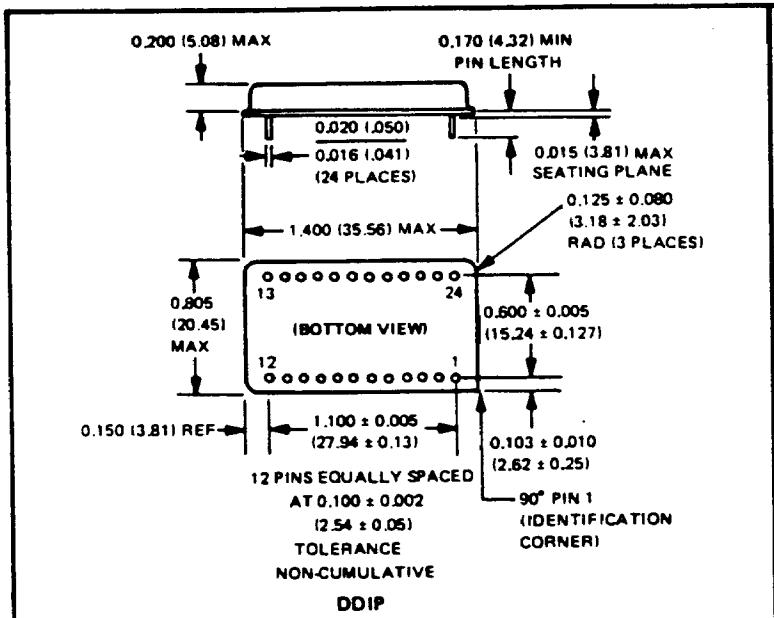
Power Supply voltage ( $V_{CCL}$ )	-0.3 to + 7.0V
Logic Input Voltage	-0.3 to +5.5V
Receiver Differential Input (RX DATA IN, RX $\overline{\text{DATA}}$ IN)	$\pm 20V$ (40Vp-p)
Receiver Input Voltage (RX DATA IN or RX $\overline{\text{DATA}}$ IN)	$\pm 15V$
Driver Output Current (TX DATA OUT or TD $\overline{\text{DATA}}$ OUT)	800mA
Transmission Duty Cycle @ $T_c = 125^\circ C$	100%
Operating Case Temperature Range ( $T_e$ )	-55°C to +125°C



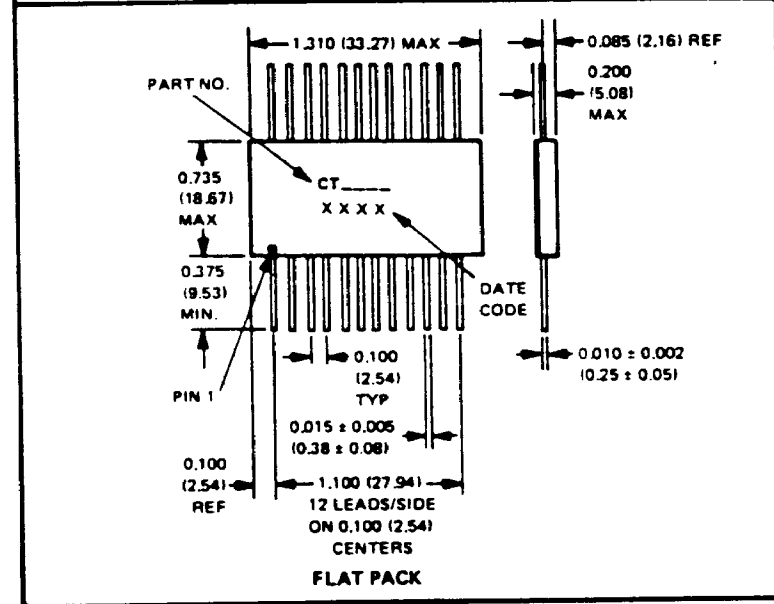
**FIGURE 3. RECEIVER LOGIC WAVEFORMS  
(FOR INVERTED DATA OUTPUT, ORDER CT2522I)**



**FIGURE 4. DRIVER LOGIC WAVEFORMS**



SINGLE UNIT (DDIP AND FLAT PACK)			
PIN	FUNCTION	PIN	FUNCTION
1	TX DATA OUT	13	N.C.
2	TX DATA OUT	14	N.C.
3	GND	15	RX DATA IN
4	N.C.	16	RX DATA IN
5	N.C.	17	N.C.
6	N.C.	18	GND
7	RX DATA OUT	19	N.C.
8	STROBE	20	+5 V
9	GND	21	TX INHIBIT
10	RX DATA OUT	22	TX DATA IN
11	N.C.	23	TX DATA IN
12	N.C.	24	N.C.



- NOTES:
1. DIMENSIONS SHOWN ARE IN INCHES (MILLIMETERS IN PARENTHESES).
  2. LEAD IDENTIFICATION NUMBERS ARE FOR REFERENCE ONLY.
  3. LEAD CLUSTER SHALL BE CENTERED WITHIN  $\pm 0.10$  (2.54) OF OUTLINE DIMENSIONS. LEAD SPACING DIMENSIONS APPLY ONLY AT SEATING PLANE.
  4. PIN MATERIAL MEETS SOLDERABILITY REQUIREMENTS OF MIL-STD-202E METHOD 208C.

- NOTES:
1. GDN PINS OF EACH SECTION SHOULD ALL BE CONNECTED EXTERNALLY.
  2. DIMENSIONS SHOWN ARE IN INCHES (MILLIMETERS IN PARENTHESES).
  3. LEAD IDENTIFICATION NUMBERS ARE FOR REFERENCE ONLY.
  4. LEAD CLUSTER SHALL BE CENTERED WITHIN  $\pm 0.10$  (2.54) OF OUTLINE DIMENSIONS. LEAD SPACING DIMENSIONS APPLY ONLY AT SEATING PLANE.
  5. PIN MATERIAL MEETS SOLDERABILITY REQUIREMENTS MIL-STD-883, METHOD 2003.
- \*LOWER PROFILE PACKAGES AVAILABLE, PLEASE CONTACT FACTORY.

FIGURE 5. MECHANICAL OUTLINE AND PINOUTS

## **RECOMMENDED DESIGN PRACTICES**

### **(a) DECOUPLING**

Decouple  $V_{CC}$  to ground, close to the hybrid with a  $>10\mu\text{F}$  tantalum capacitor in parallel with a 100nF ceramic bypass capacitor.

Note: Peak transmission current drawn from  $V_{CC}$  is 650mA.

### **(b) PCB LAYOUT**

- Full PCB ground-planing is recommended.
- It is good practice to ensure connections from encoder/decoder to 'TXLOGICIN', 'TXLOGICIN' and 'TXINHIBIT' are as short as possible and of balanced length, shape and area. Optimum results are obtained when these signals have minimum rise/fall times and minimum differential delays.
- Connections between 'TXDATAOUT' and the center tapped transformer should be designed to:
  - (i) Withstand peak transmission currents at required operating duty cycles
  - (ii) Minimize added series inductance
  - (iii) Ensure system capacitance in conjunction with transceiver and transformer impedances does not reduce overall input impedance below the value stated in MIL-STD-1553B.

These connections should also be balanced in terms of length, shape and area.

*The information presented herein is to the best of our knowledge true and accurate. No warranty expressed or implied is made regarding the capacity, performance or suitability of any product. You are strongly urged to ensure that the information given has not been superseded.*

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